PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Jonathan A. Noquil	07/16/2004
Seung-Yong Choi	07/16/2004
Rajeev D. Joshi	07/19/2004
Chung-Lin Wu	07/19/2004

RECEIVING PARTY DATA

Name:	Fairchild Semiconductor Corporation
Street Address:	82 Running Hill Road
Internal Address:	MS 35-4C
City:	South Portland
State/Country:	MAINE
Postal Code:	04106

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	10803464

CH $40.00 10803464

CORRESPONDENCE DATA

Fax Number: (585)325-5458
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
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Correspondent Name: Thomas R. FitzGerald, Esq.
Address Line 1: Hiscock & Barclay, LLP
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ATTORNEY DOCKET NUMBER:	3016271 (90065.001400)
NAME OF SUBMITTER:	Thomas R. FitzGerald

Total Attachments: 4
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FAIRCHILD SEMICONDUCTOR CORPORATION

Assignment

As a below named inventor or joint inventor of an invention or improvement entitled:

MULTI-FLIP CHIP ON LEAD FRAME ON OVER
MOLDED IC PACKAGE AND METHOD OF ASSEMBLY

(U. S. Serial Number 10/803,464, filed March 18, 2004)

for which I have executed an application for Letters Patent of the United States of America, on an even date herewith; and

WHEREAS, FAIRCHILD SEMICONDUCTOR CORPORATION, a Corporation, organized and existing under the laws of the State of Delaware, having its principal office and place of business in the City of South Portland, State of Maine, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have sold, assigned, transferred, and set over, and by these presents do hereby sell, assign, transfer and set over, unto said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, my entire right, title and interest in, to, and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuation applications thereof, and all Letters Patent of the United States of America which may be granted thereof and all reissues and extensions hereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention, all rights to register said invention in appropriate registries, and all Letters Patent which may be granted for said invention in any country or countries foreign to the Unites States of America, and all extensions, renewals, and reissues thereof, and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, in accordance with the terms of this instrument.

And I hereby covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

And I hereby further covenant and agree that I will communicate to said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, any fact known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisions, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid said FAIRCHILD SEMICONDUCTOR CORPORATION, its successors, legal representatives, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN TESTIMONY WHEREOF, I authorize and affirm said assignments with the signature(s) set forth below on the indicated date(s).

Inventor:

16 July 2004

Jonathan A. Noquil Date

S Y Choi 16 Jul. 2004

Seung-Yong Choi Date

Rajeev Joshi Date

Chung-Lin Wu Date

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IN TESTIMONY WHEREOF, I authorize and affirm said assignments with the signature(s) set forth below on the indicated date(s).

Inventor:

Jonathan A. Noquil	Date
Seung-Yong Choi	Date
RJoshi Rajeev Joshi	Jul. 19, 2004 Date
Chung-Lin Wu	July 19, 2004 Date